

WHAT IS CLAIMED IS:

- 1 1. A method for manufacturing printed circuit boards comprising:
2 placing a component on a circuit board;
3 partially printing attachment media on the circuit board with a pressurized
4 squeegee head containing at least one blocking cap, wherein no attachment media
5 is printed onto the component; and
6 placing additional components on the circuit board.
- 1 2. The method of claim 1 wherein the component is a die.
- 1 3. The method of claim 2 further comprising testing the die prior to the partial
2 printing step.
- 1 4. The method of claim 1 wherein the attachment media is solder paste, liquid
2 flux or adhesive paste.
- 1 5. The method of claim 1 further comprising shipping the circuit board to
2 another location before the partial printing step.
- 1 6. The method of claim 1 further comprising reflowing the attachment media
2 and performing in-circuit testing.
- 1 7. The method of claim 1 wherein the pressurized squeegee head contains two
2 blocking caps.
- 1 8. The method of claim 1 wherein the pressurized squeegee head contains three
2 blocking caps.
- 1 9. The method of claim 1 wherein the pressurized squeegee head contains four
2 or more blocking caps.

- 1 10. A method comprising:
2 placing a component on a circuit board;
3 shipping the circuit board to another location;
4 partially printing attachment media on the circuit board with a pressurized
5 squeegee head containing at least one blocking cap, wherein no attachment media
6 is printed onto the component; and
7 placing additional components on the circuit board.
- 1 11. The method of claim 10 wherein the component is a die.
- 1 12. The method of claim 11 further comprising testing the die prior to the partial
2 printing step.
- 1 13. The method of claim 10 wherein the attachment media is solder paste, liquid
2 flux or adhesive paste.
- 1 14. The method of claim 10 further comprising reflowing the attachment media.
- 1 15. The method of claim 14 further comprising performing in-circuit testing.
- 1 16. A method for manufacturing printed circuit boards comprising:
2 placing a die on a circuit board;
3 partially printing solder paste on the circuit board with a pressurized
4 squeegee head containing at least one blocking cap, wherein no solder paste is
5 printed onto the die; and
6 placing additional components on the circuit board.
- 1 17. The method of claim 16 further comprising testing the die prior to the partial
2 printing step.

1 18. The method of claim 17 further comprising shipping the circuit board to
2 another location before the partial printing step.

1 19. The method of claim 18 further comprising reflowing the solder paste.

1 20. The method of claim 19 further comprising performing in-circuit testing.